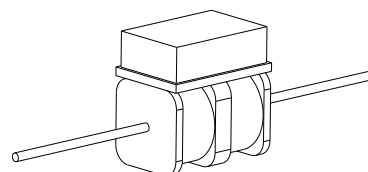


- Size Design 8.8mm*6.2mm*8.7mm
- High Current Handling Capability 3kA @ 8/20μs
- Fast Response and Long Service Life
- Moisture sensitivity level: Level 1
- Low impulse Voltage



Application information

- AC Power

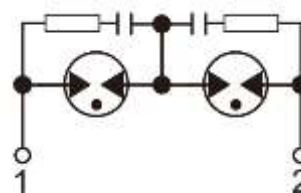
Package (Top View)



Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

Schematic Symbol



Electrical Parameter

DC Breakdown Voltage ^{1) 2)}	100V/s	3200~4800	V
Impulse Spark-over Voltage ^{1) 2)}	At 1kV/μs	for 99 % of measured values ≤ 3000	V
		Typical values of distribution ≤ 2500	V
Impulse Discharge Current ³⁾	8/20μs ±5times	3	kA
Arc Voltage	At 1A	~35	V
Insulation Resistance	DC=100V	≥1	GΩ
Capacitance at 1 MHz	V _{DC} =0.5V	≤500	pF
Hi-pot Test ^{1) 2)}	I _D =0.5mA	≥2000	VAC
Operating and storage Temperature		-40~105	°C
Marking		Bencent Logo	

1) At delivery AQL 0.65 level II ISO 2859

2) In ionized mode

3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Part Numbering System

BXD 3000 SA03 M - D

(1) (2) (3) (4) (5)

(1)Bencent pulse sensitive Gas Discharge Tube

(2)DC Breakdown Voltage, e.g.,3200~4100V

(3)SA03:3kA

(4)M:20% K:10%

(5) “D” means the special structure of this type

Product Characteristics

Lead Material	Copper
Body Material	Ceramics、epoxy
Terminal Finish	100% Matte-Tin Plated

Environmental Reliability Characteristics

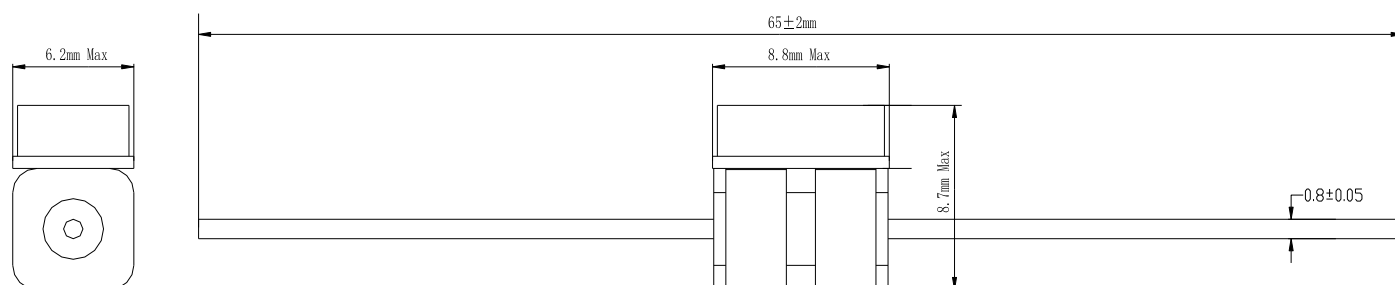
Testing items	Technical standards
High Temperature Storage Test	Temperature: 105℃ Time:2H
Low Temperature Storage Test	Temperature: -40℃ Time:2H
Vibration	Frequency: 10-100Hz Amplitude: 0.15mm Time: 45min
Resistance of soldering heat	Temperature: 260±5℃ Time of dip soldering: 10s, 1time

Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability test

Solderability	Solder Pot Temperature:	245℃ ± 5℃
	Solder Dwell Time:	4-6 seconds

Product Dimensions

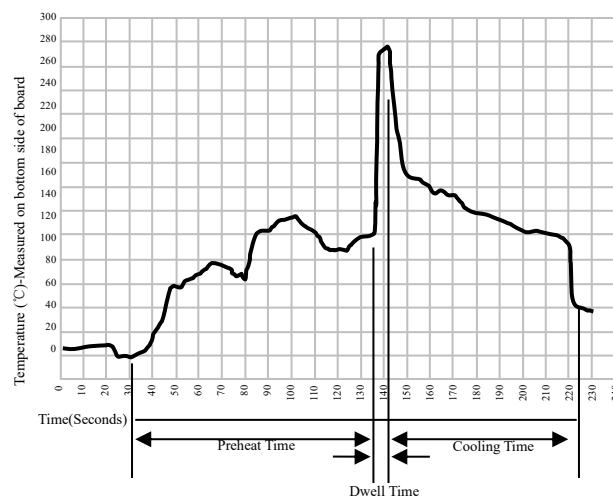


Wave Solderingprofile

Wave Soldering Condition		Pb-Free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time (min to max)	60 – 180 secs
Solder Pot Temperature		260°C Max
Solder Dwell Time		2-5 seconds

Notice:

This product does not support reflux welding.



Packaging Information

Manner of packing	Blister Box (PCS)	Inner Carton (PCS)	Per Carton (PCS)	Inner Box Diameter (mm)	Carton Size(mm)		
					L	W	H
Box-packed	110	990	5940	210*180*110	390	370	220